景 碩 科 技 股 份 有 限 公 司

Kinsus Interconnect Technology Corp.

Aug 2025

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IC 封裝技術
IC Packaging Technology

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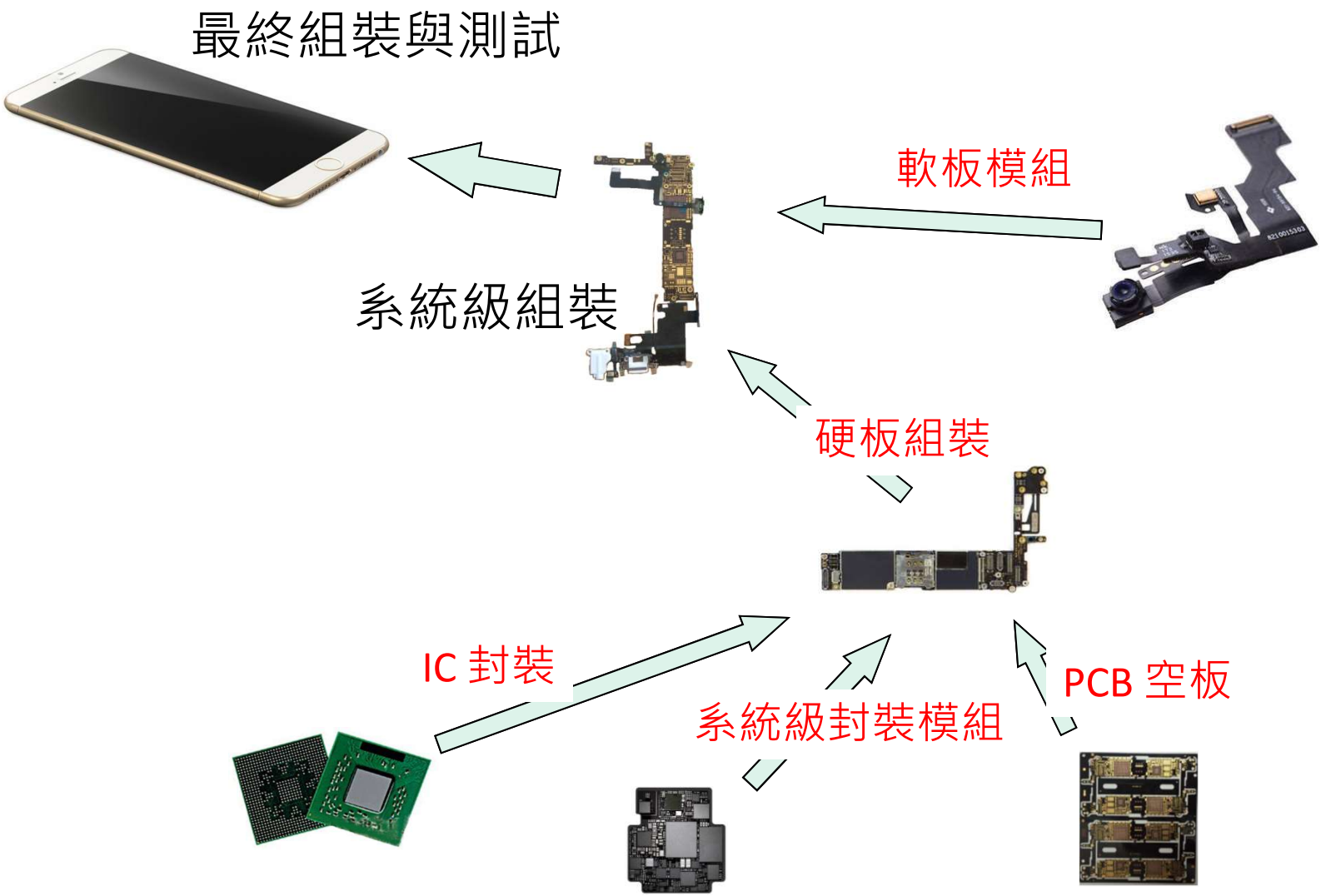
電子產品構裝的各個層次



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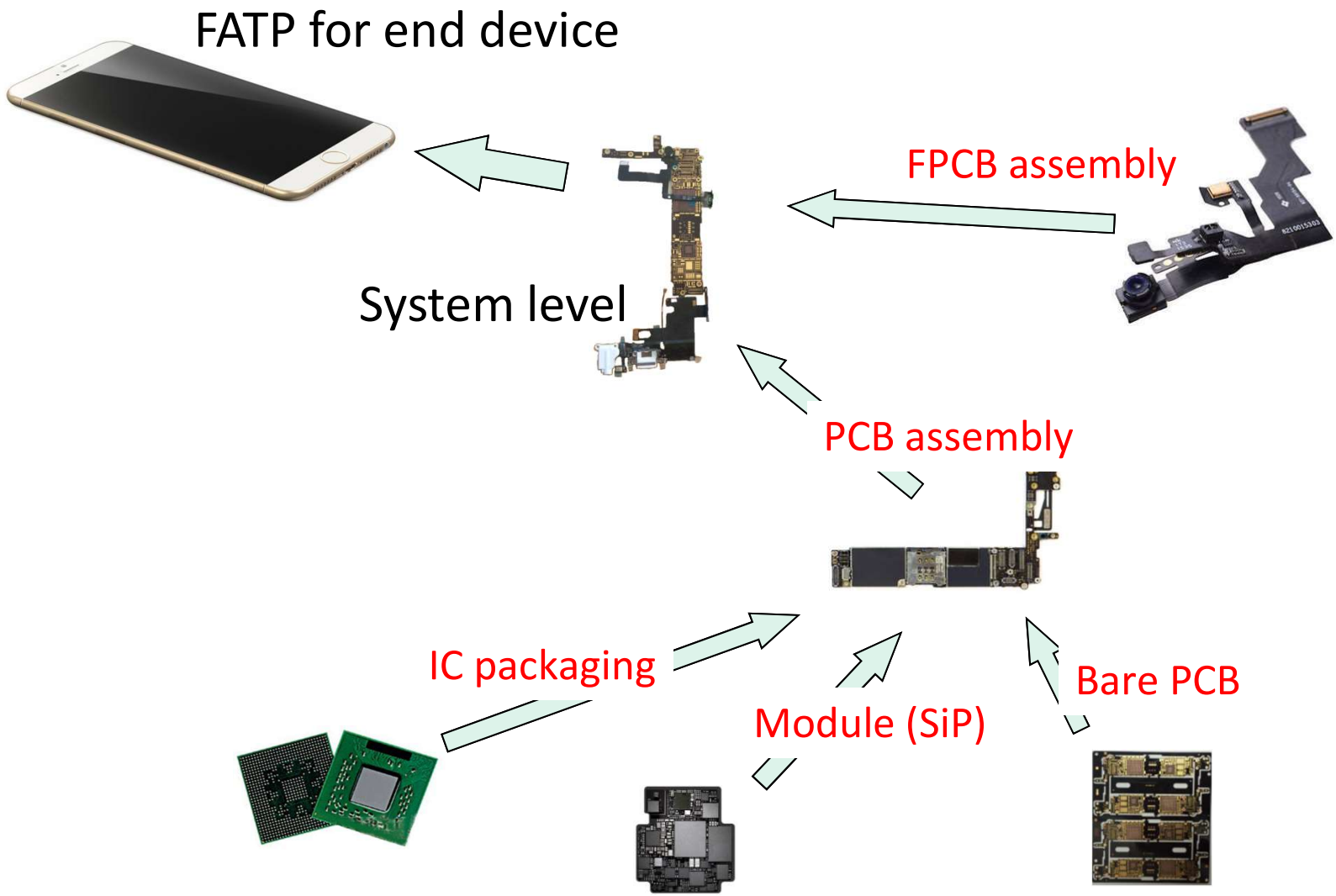
Levels of Assembly



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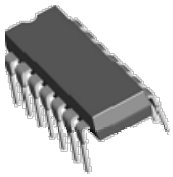
各種形式的IC 封裝



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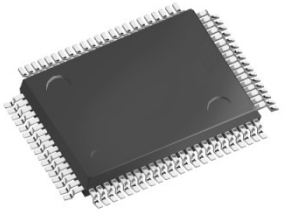
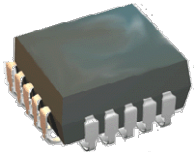
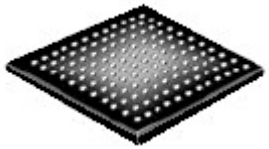


QFP



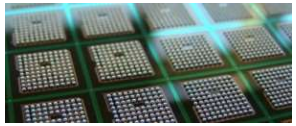
PLCC

TSOP

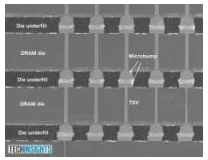


PBGA/
Flip-Chip BGA

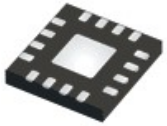
CSP



WLP

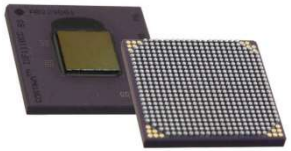


TSV

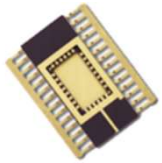


QFN

DFN



Ceramic BGA



Ceramic chip

BGA 封裝 市場規模: 2023 年828 億顆, 產值 161億美元

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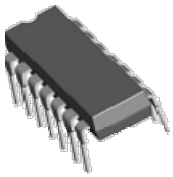
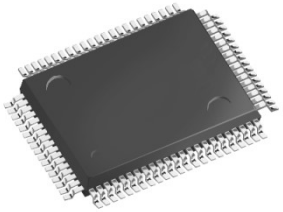
Different types of IC packaging



DIP



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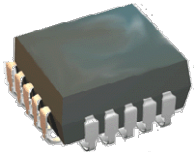
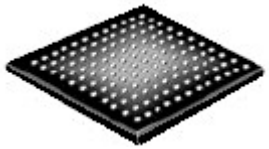


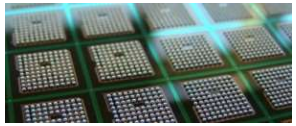
PLCC

TSOP



PBGA/
Flip-Chip BGA

CSP



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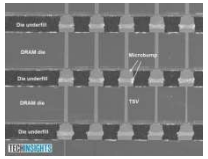

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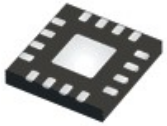

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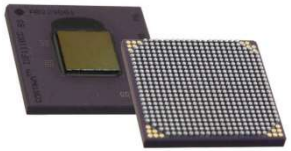
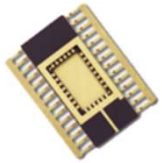


Ceramic BGA



Ceramic chip

BGA Market size : 82 Billion units, 16 Billion US$ in 2023

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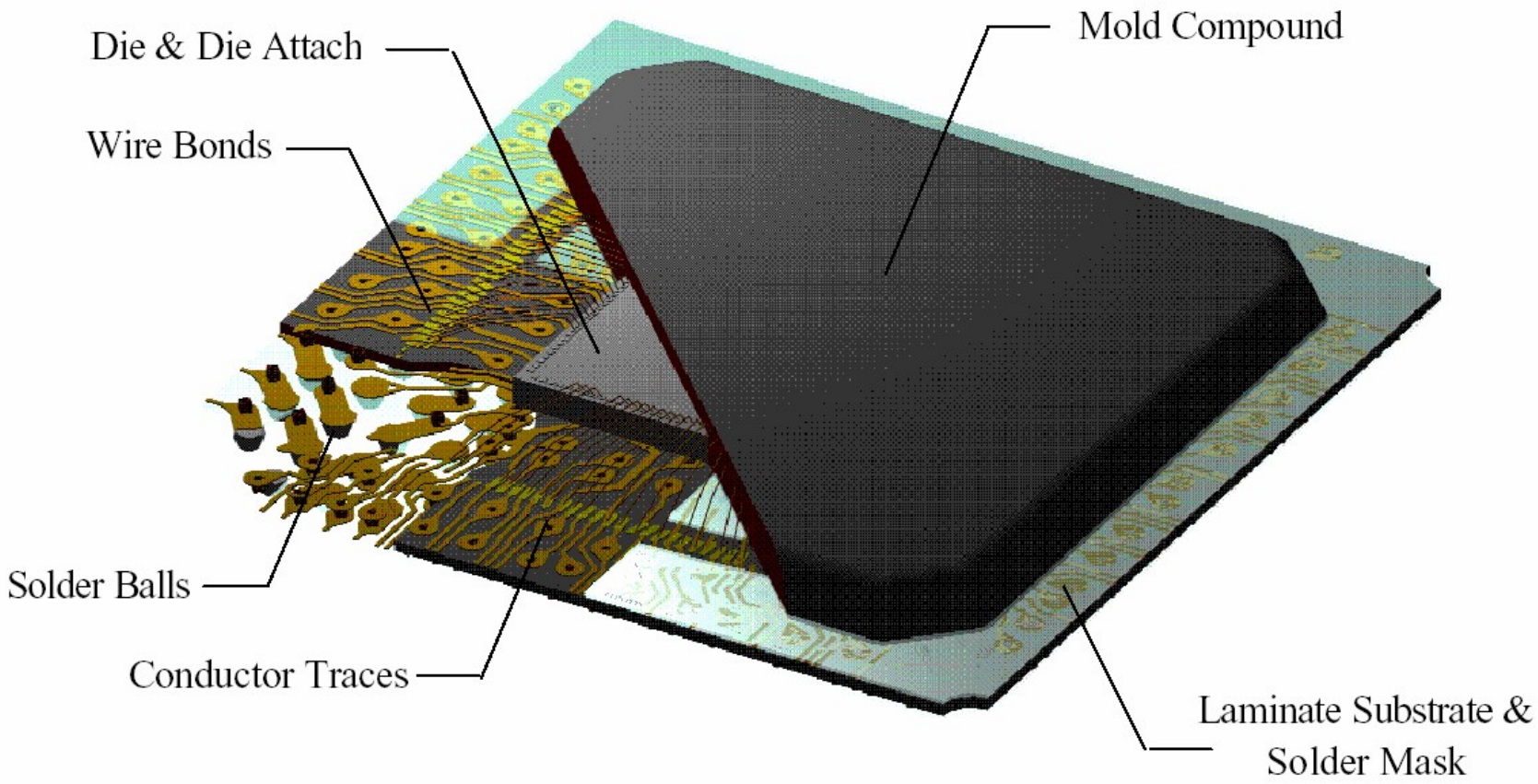
IC 結構



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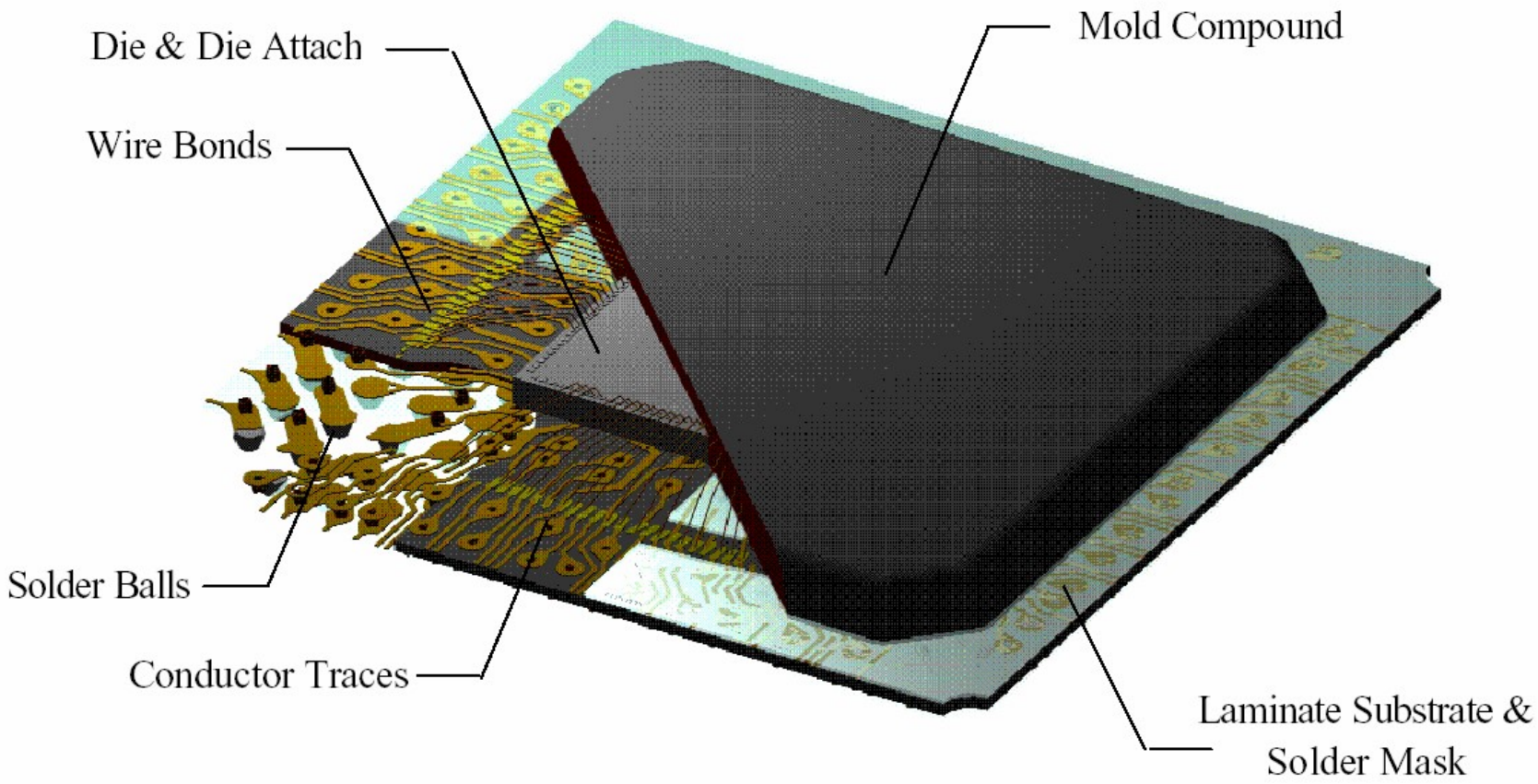
What Substrate Makers do?



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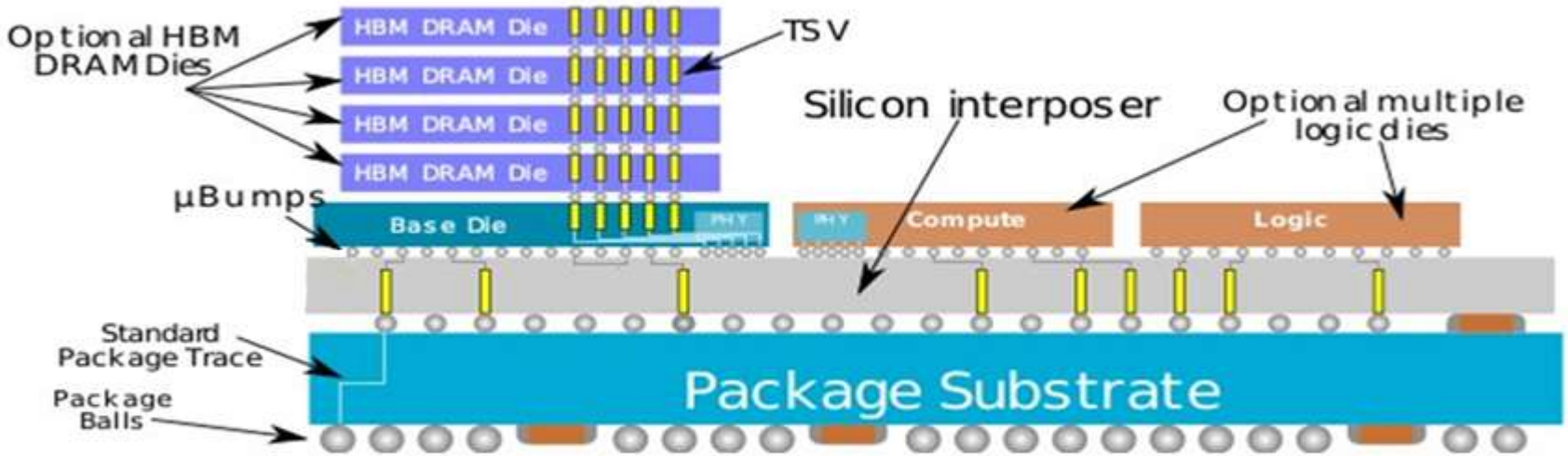
先進封裝結構

CoWoS



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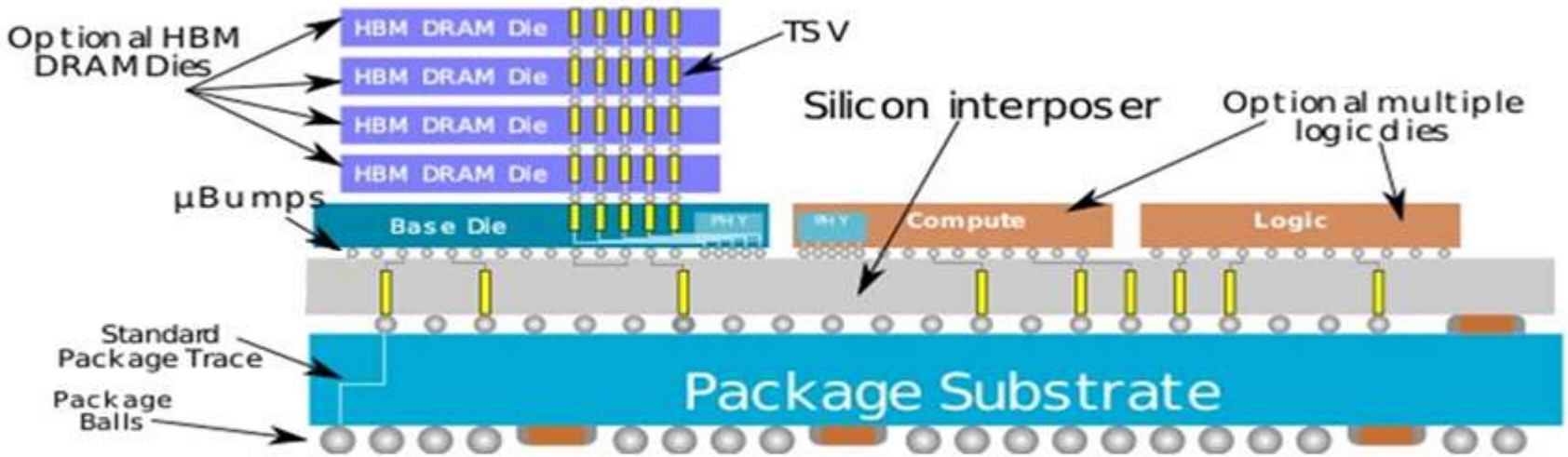
Advanced Packaging

CoWoS



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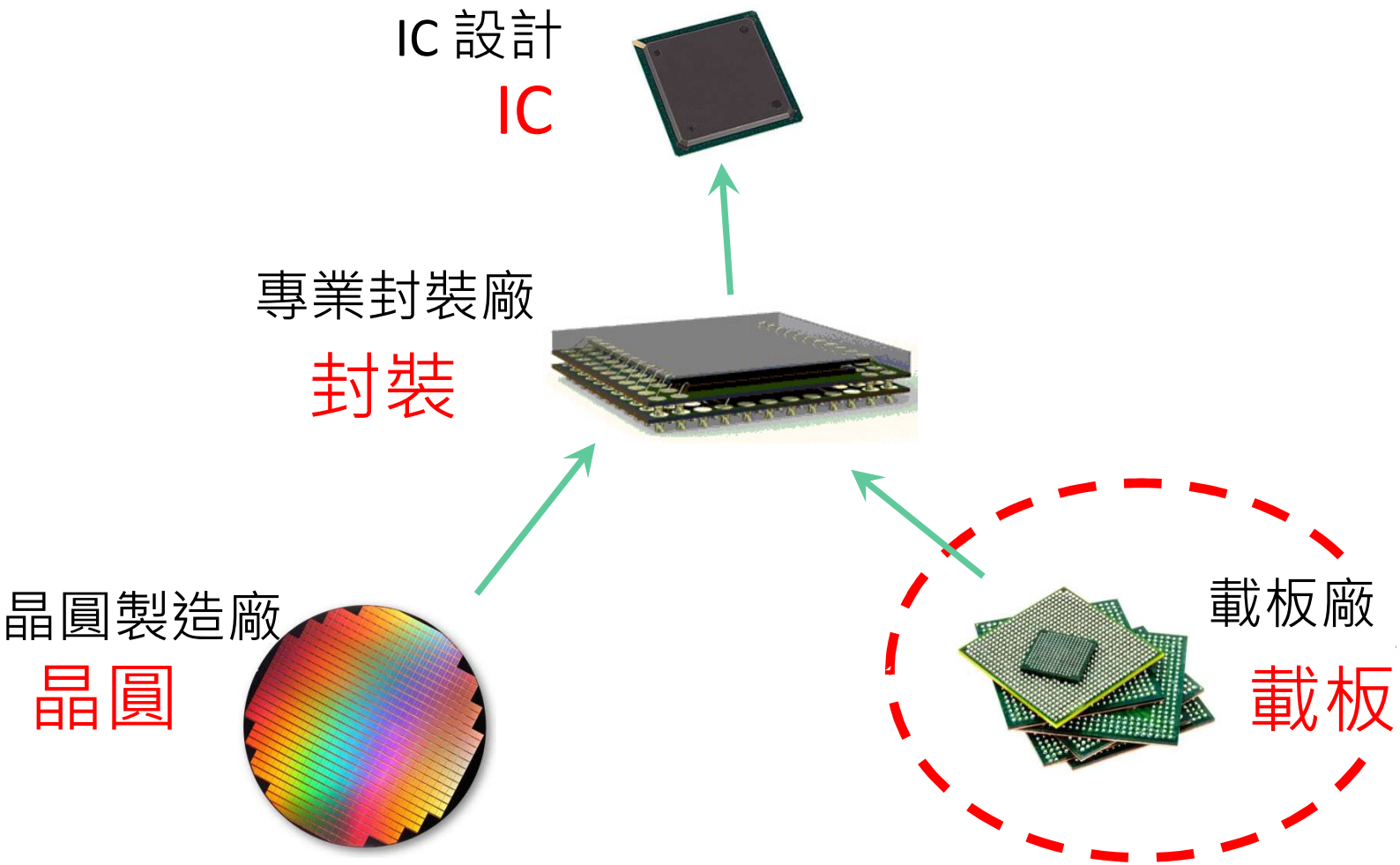
IC 半導體上下游供應鏈關係



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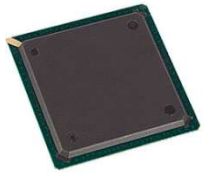
IC Manufacturing Supply Chain

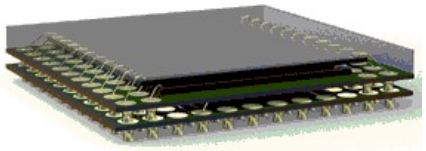
IC Design (Fabless)

IC



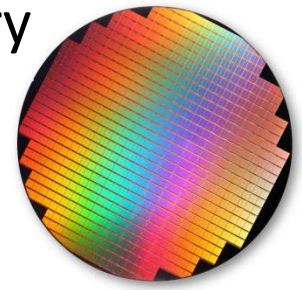
OSAT

Packaging



Foundry

Wafer



Substrate house

Substrate

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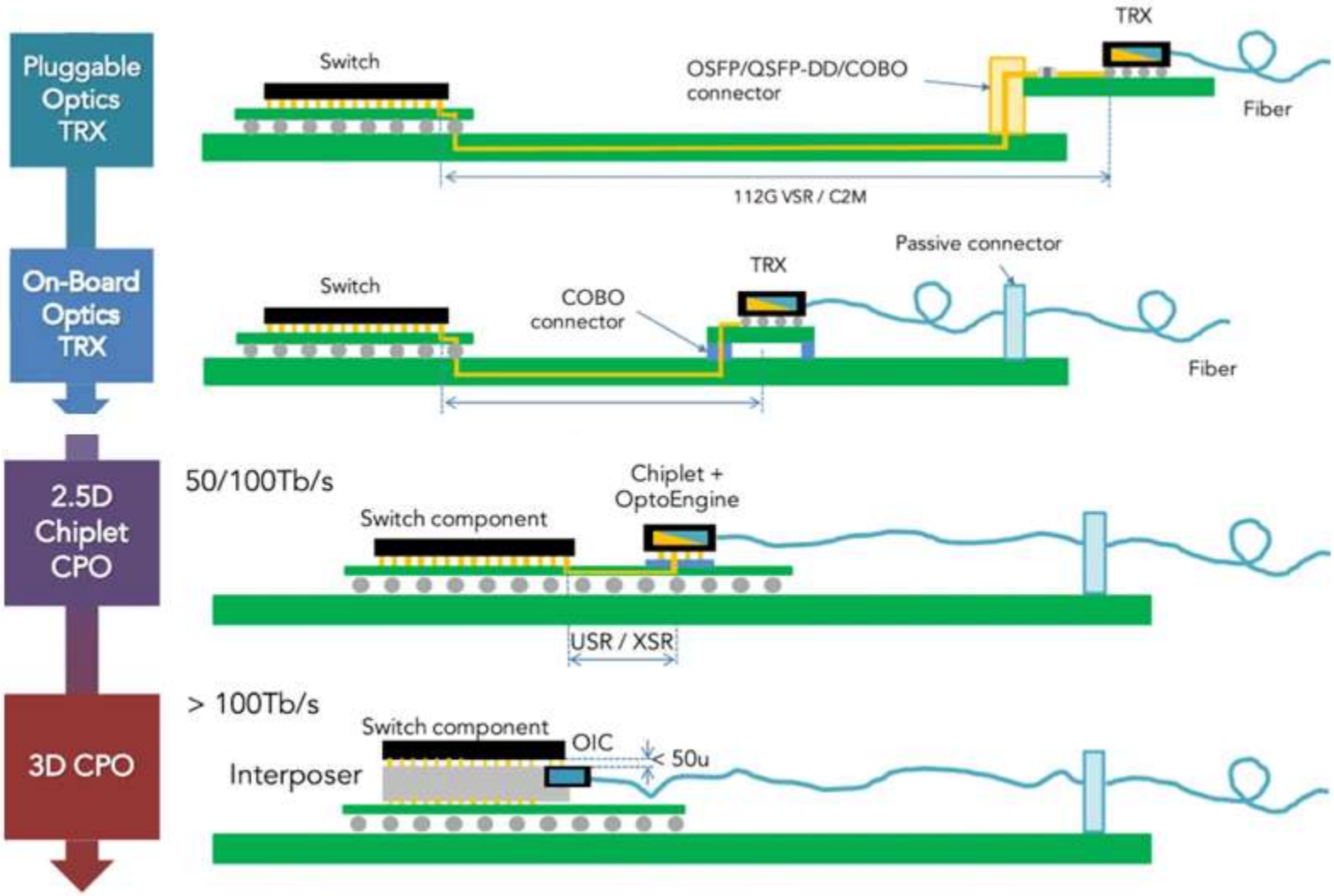
光學共構封裝



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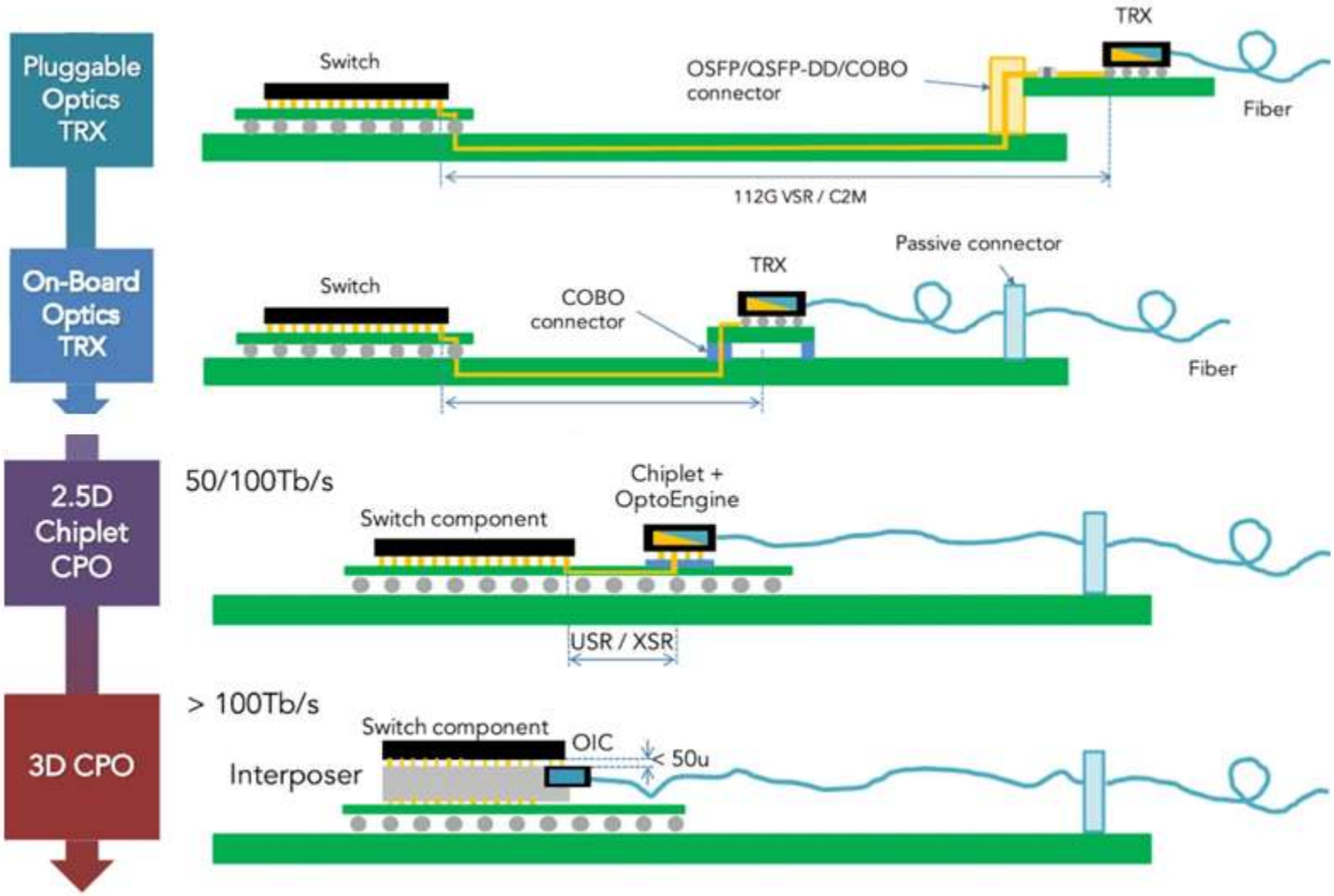
Co-Packaged Optics



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About Kinsus

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基本資料

- 公司成立 2000
  台股上市掛牌 2004
- 資本額： 新台幣 45.45 億元
- 廠區： 總部 - 新屋 / 台灣
  IC 載板 - 一廠 及 二廠
  - 五廠 及 六廠
  Kinsus USA - Santa Clara / California
  統碩科技 - 蘇州 / 中國
  晶碩光學 - 桃園 / 台灣

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Basic Information

- Established in September 2000
  IPO at TWSE in November 2004
- Capital : US$ 147 Million (NT$ 4.545 Billion)
- Campus :

Headquarters	- Xin Wu / Taiwan
IC substrates	- Plant 1 & 2
	- Plant 5 & 6
Kinsus USA	- Santa Clara / California
Kinsus China	- Suzhou / China
PegaVision	- Taoyuan / Taiwan

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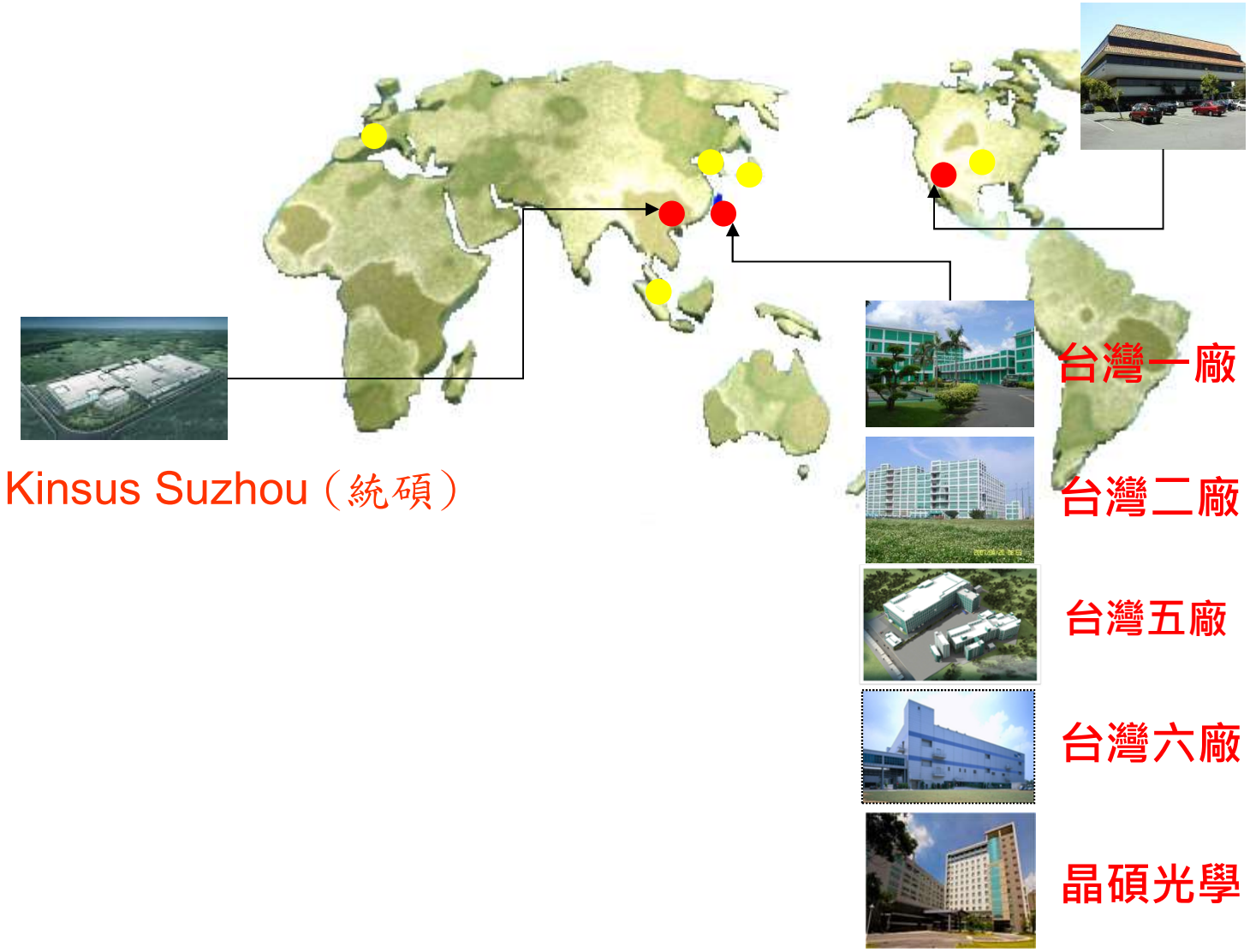
位置



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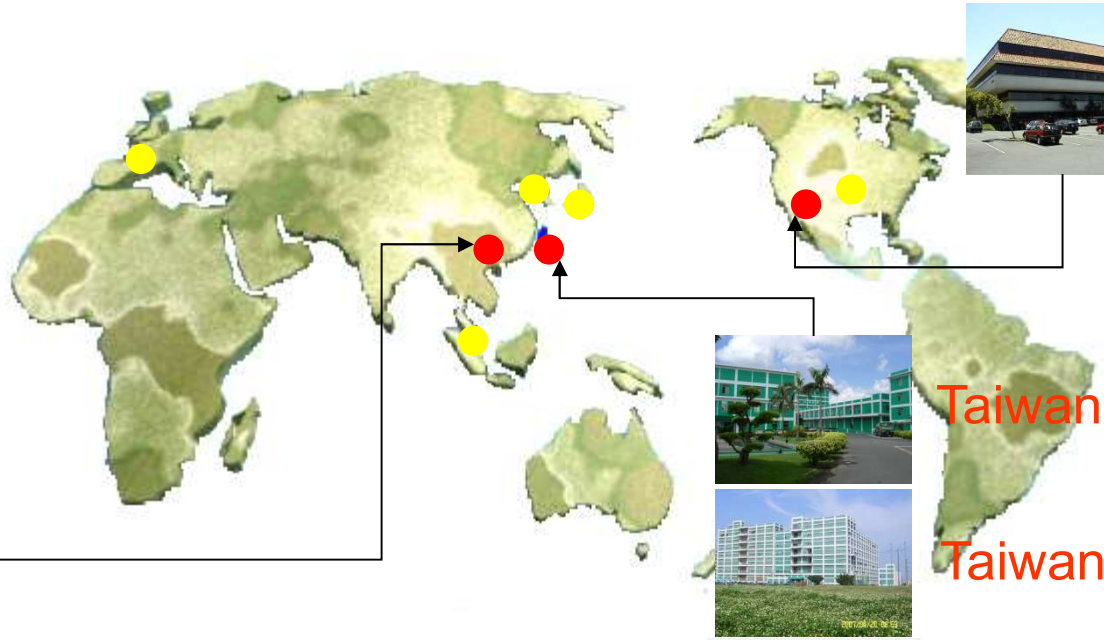
Locations



Kinsus USA

Taiwan plant 1

Taiwan plant 2

Taiwan plant 5

Taiwan plant 6

PegaVision

Kinsus Suzhou（統碩）

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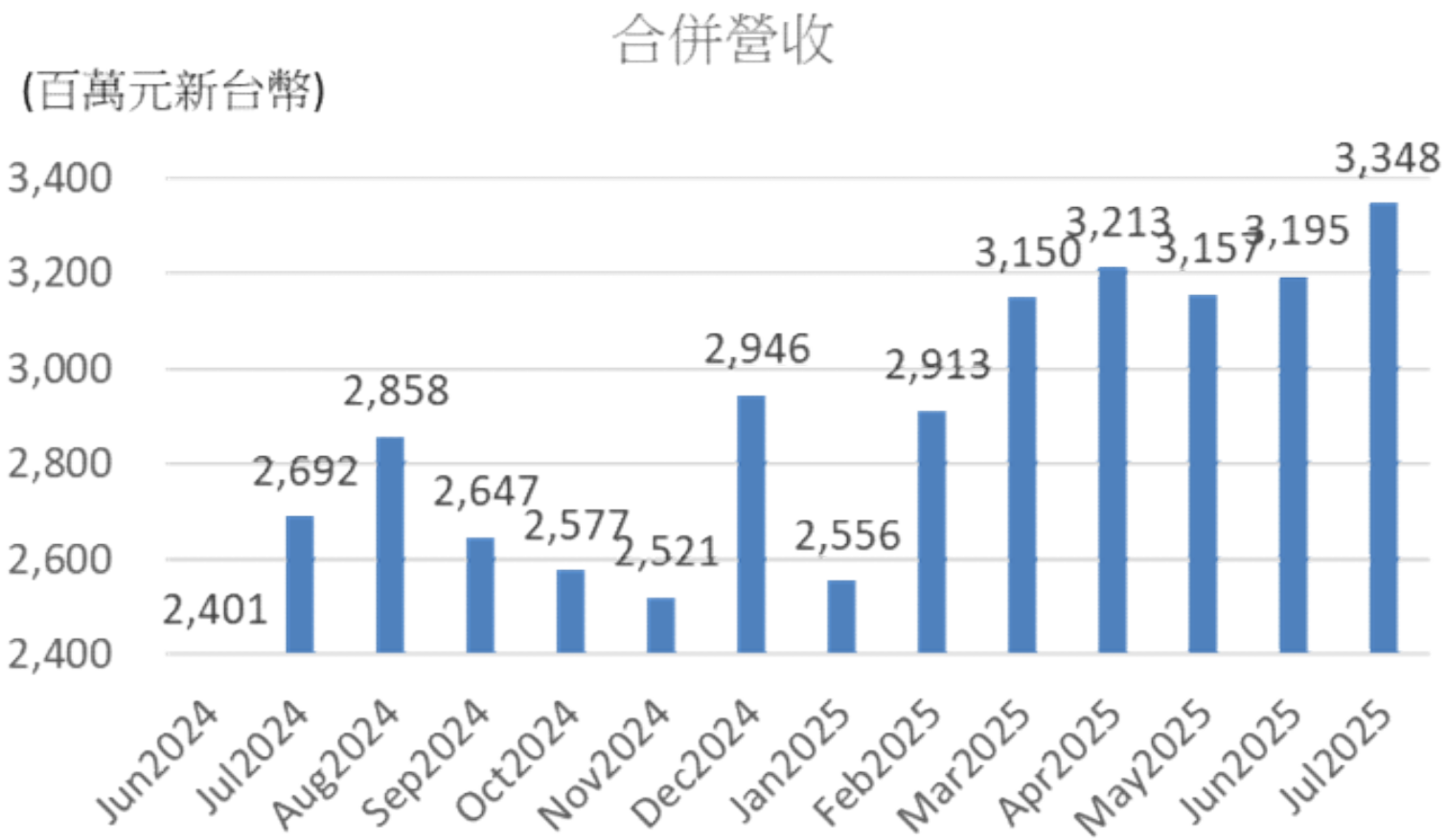
每月合併營業額



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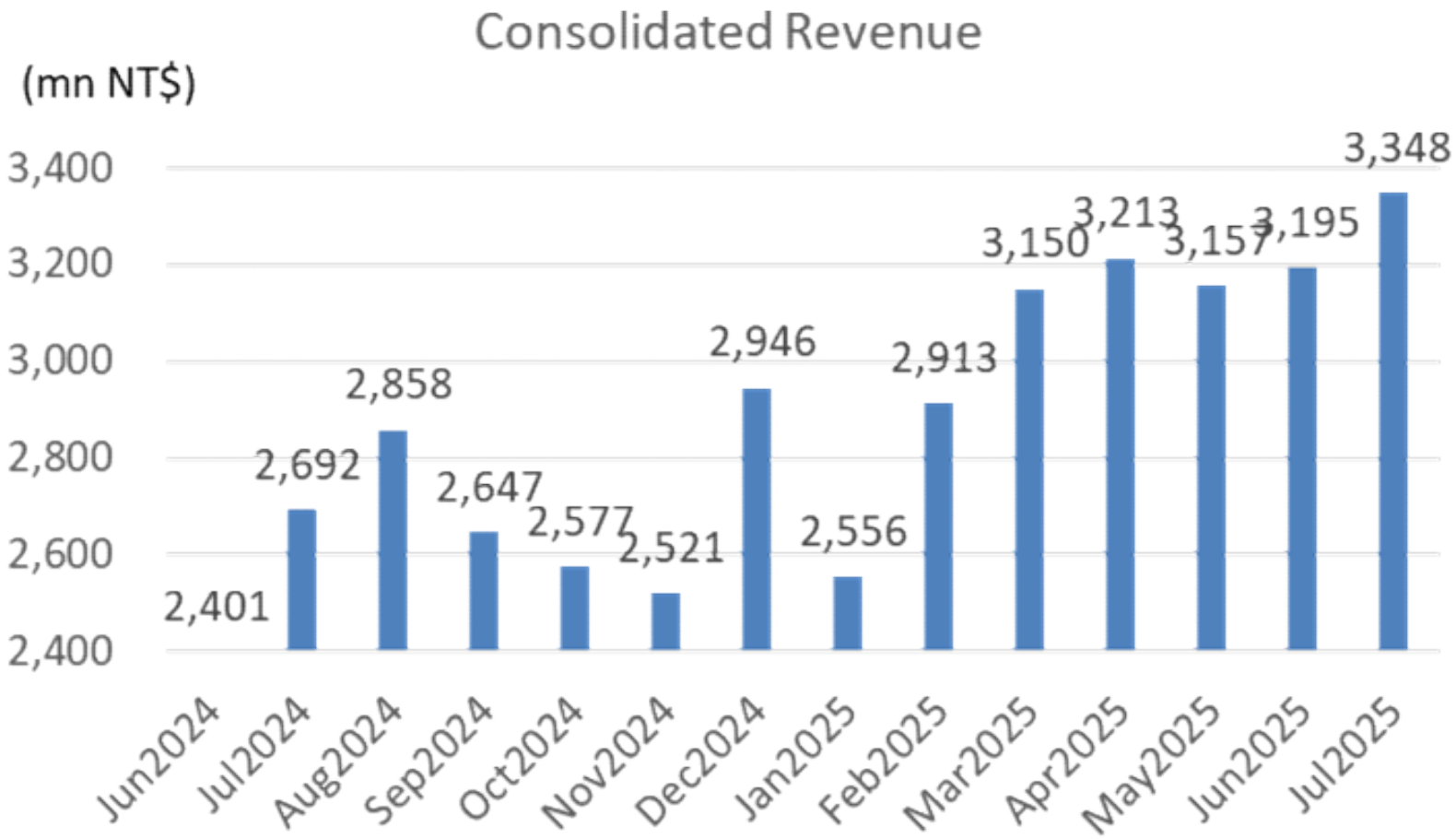
Monthly Consolidated Revenue



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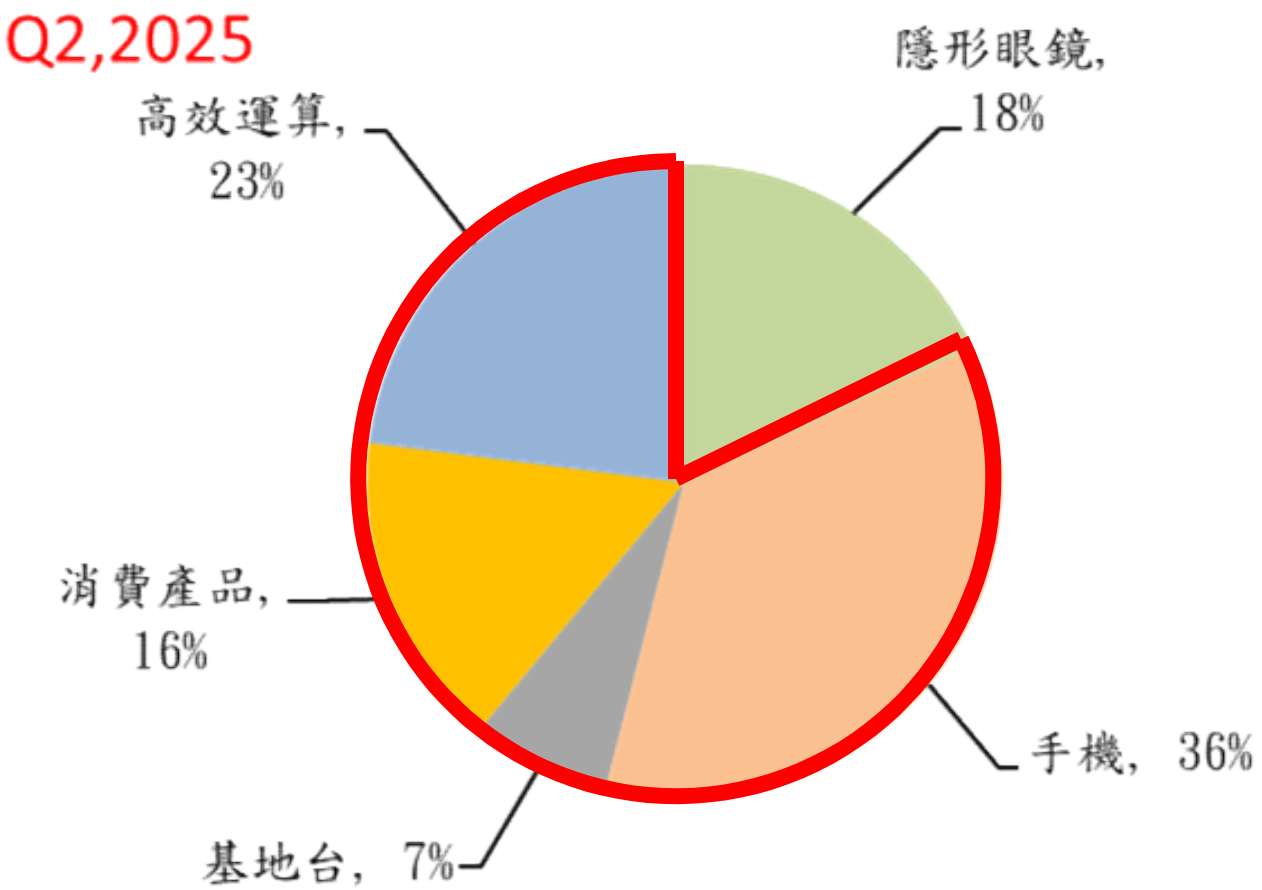
產品組合



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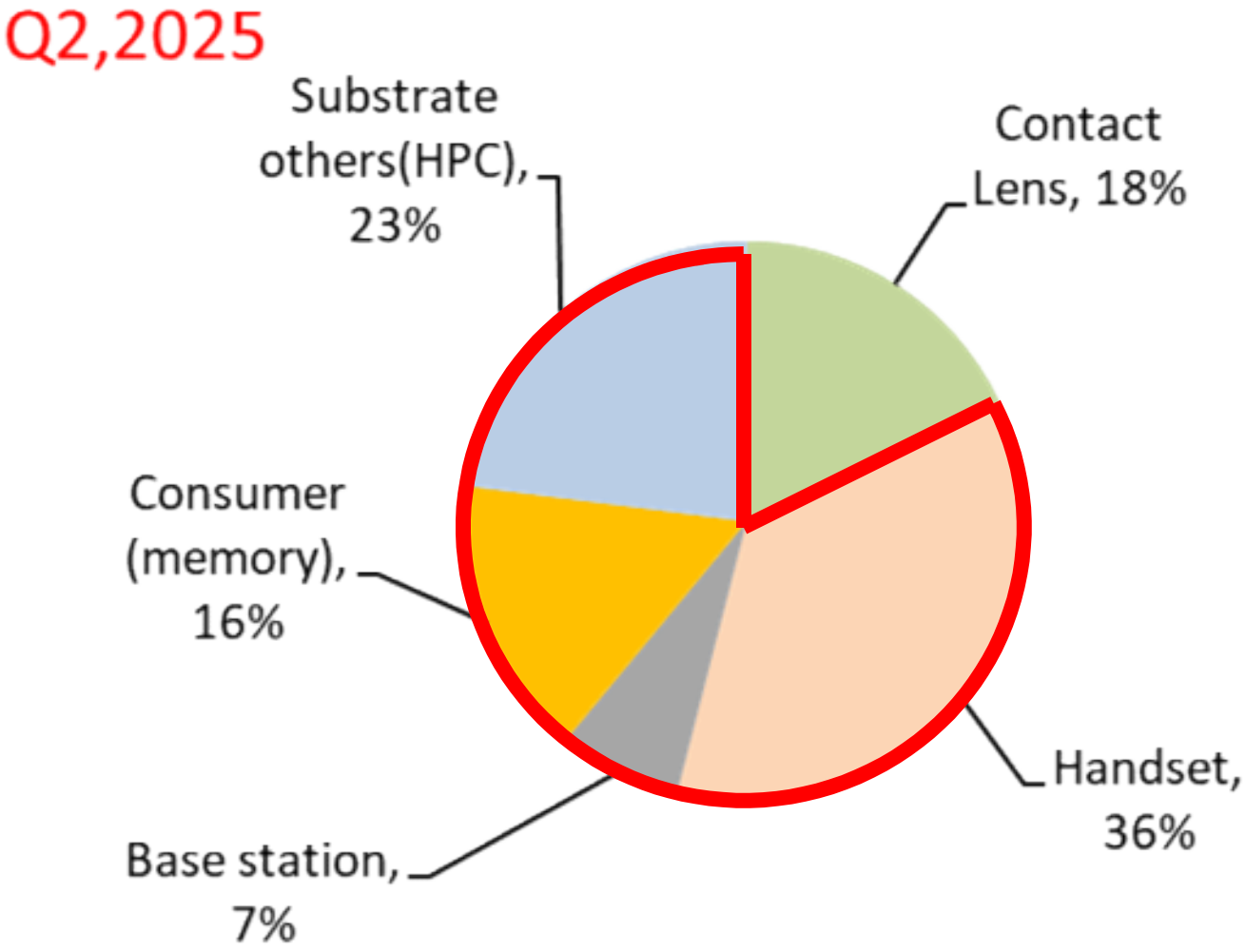
Product mix



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競爭格局

BT-Flip Chip

BT-wire bond

ABF-Flip Chip

Kinsus

SEMCO

LG Innotek

ASEM

南亞電路板 NAN YA PCB

SIMMTECH

SCC 深南电路

臻鼎科技集團 Zhen Ding Tech. Group

IBIDEN

SHINKO

AT&S

Unimicron

BGA

SiP

CSP/PBGA

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Competition Landscape

BT-Flip Chip

BT-wire bond

ABF-Flip Chip

Kinsus

SEMCO

LG Innotek

ASEM

南亞電路板 NAN YA PCB

SIMMTECH

SCC 深南电路

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IBIDEN

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AT&S

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BGA

SiP

CSP/PBGA

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Thank you

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